

Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. MP0115	Application No. To be assigned 09/966914
Information Disclosure Statement by Applicant (Use several sheets if necessary) (37 CFR §1.98(b))		Applicant Sehat Sutardja	Group Art Unit To be assigned 2884
		Filing Date HEREWITH	

U.S. Patent Documents

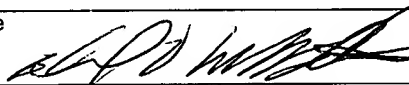
Examiner Initial	Desig. ID	Patent Number	Issue Date	Patentee	Class	Subclass	Filing Date If Appropriate
Dr	AA	5,355,283	10/11/94	Marrs et al.			
Dr	AB	5,729,050	03/17/98	Jin Sung Kim			
Dr	AC	5,729,440	03/17/98	Jimarez et al.			
Dr	AD	5,869,894	02/09/99	Degani et al.			
Dr	AE	5,959,348	09/28/99	Chang et al.			
Dr	AF	6,020,646	02/01/00	Boyle et al.			
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Dr	AH	6,096,981	08/01/00	Vinciarelli et al.			
Dr	AI	6,150,724	11/21/00	Wenzel et al.			
Dr	AJ	6,175,158 B1	01/16/01	Degani et al.			
Dr	AK	6,232,661 B1	05/15/01	Amagai et al.			
Dr	AL	6,242,815 B1	06/05/01	Hsu et al.			
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Foreign Patent Documents or Published Foreign Patent Applications

Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
Dr	AN	19821916 A1	03/11/99	Germany				
	AO							

Other Documents (include Author, Title, Date, and Place of Publication)

Examiner Initial	Desig. ID	Document
Dr	AP	Bober et al., "Current Trends in Flip-Chip Bonding Technique for Multichip Modules - especially Micro-Jet Printing," Inst. of Microsystem Tech., Wroclaw U. of Tech., Wroclaw, Poland, Conference 2000, pp. 1-14, via iMaps.
Dr	AQ	Amkor Technology, www.amkor.com, Advanced package glossary, pp. 1-4, 03/01.
	AR	

Examiner Signature 	Date Considered 7/28/02
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	